RoHS

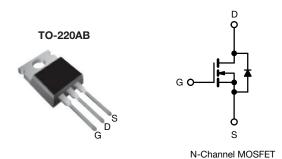
COMPLIANT

HALOGEN

FREE



# **E Series Power MOSFET**



PRODUCT SUMMA	RY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650	)
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.082
Q <sub>g</sub> max. (nC)	132	2
Q <sub>gs</sub> (nC)	22	
Q <sub>gd</sub> (nC)	46	
Configuration	Sing	le

#### **FEATURES**

- A specific on resistance (m $\Omega$ -cm $^2$ ) reduction of 25 %
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

### **APPLICATIONS**

- Power factor correction power supplies (PFC)
- · Hard switching PWM stages
- Computing
  - Switch mode power supplies (SMPS)
- Lighting
  - Light emitting diode (LED)
  - High intensity discharge (HID)
- Telecom
  - Server power supplies
- Renewable energy
  - Photovoltaic inverters
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Uniterruptable power supplies

ORDERING INFORMATION	
Package	TO-220AB
Load (Dh) free and helegen free	SiHP35N60E-BE3
Lead (Pb)-free and halogen-free	SiHP35N60E-GE3

ABSOLUTE MAXIMUM RATINGS (TC	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			$V_{DS}$	600	V
Gate-source voltage		$V_{GS}$	± 30	7 v	
Continuous drain current (T <sub>.I</sub> = 150 °C)	V -+ 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		32	
Continuous drain current (1 <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	20	A
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	80	
Linear derating factor				2	W/°C
Single pulse avalanche energy b			E <sub>AS</sub>	691	mJ
Maximum power dissipation			$P_{D}$	250	W
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope	T <sub>J</sub> = 125 °C		-1) //-14	57	1//
Reverse diode dV/dt <sup>d</sup>			dV/dt	31	- V/ns
Soldering recommendations (peak temperature) c	For	10 s		300	°C

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 7 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.5	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				<b>!</b>			
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.70	-	V/°C
Gate-source threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
Cata animan lankana		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage	$I_{GSS}$	\	$I_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zovo goto voltogo dvoje ovevent		V <sub>DS</sub> =	600 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	25	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 17 A	-	0.082	0.094	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> :	= 30 V, I <sub>D</sub> = 17 A	-	13	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$		-	2760	-	pF
Output capacitance	C <sub>oss</sub>	, ·	$V_{DS} = 100 \text{ V},$		118	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		-	5	-	
Effective output capacitance, energy related <sup>a</sup>	$C_{o(er)}$	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	118	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	429	-	
Total gate charge	Qg			-	88	132	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V I <sub>D</sub> = 17 A, V <sub>DS</sub> = 480 V		-	22	-	nC
Gate-drain charge	Q <sub>gd</sub>	7		-	46	-	1
Turn-on delay time	t <sub>d(on)</sub>			-	29	58	
Rise time	t <sub>r</sub>	$V_{DD} = 480 \text{ V}, I_{D} = 17 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	61	92	ns
Turn-off delay time	t <sub>d(off)</sub>			-	78	117	
Fall time	t <sub>f</sub>			-	32	64	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.25	0.5	1	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	Is	MOSFET sym showing the	MOSFET symbol showing the		-	32	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	80	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 17 A, V <sub>GS</sub> = 0 V	-	0.9	1.2	V
Reverse recovery time	t <sub>rr</sub>	-		-	455	910	ns
Reverse recovery charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $dI/dt = 100 \text{ A/µs}, V_R = 25 \text{ V}$		-	8	16	μC
Reverse recovery current	I <sub>RRM</sub>			_	30	-	A

### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ 

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ 



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

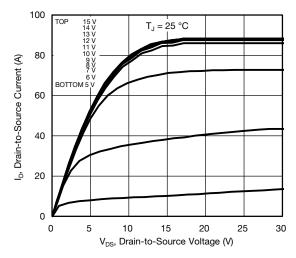


Fig. 1 - Typical Output Characteristics

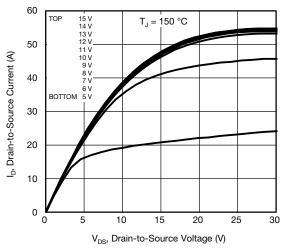


Fig. 2 - Typical Output Characteristics

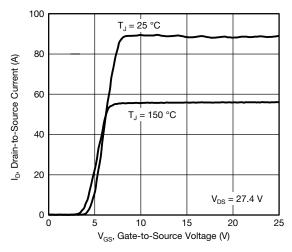


Fig. 3 - Typical Transfer Characteristics

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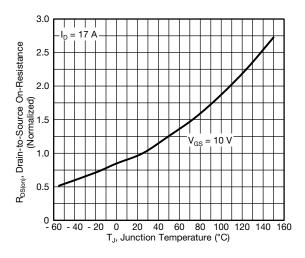


Fig. 4 - Normalized On-Resistance vs. Temperature

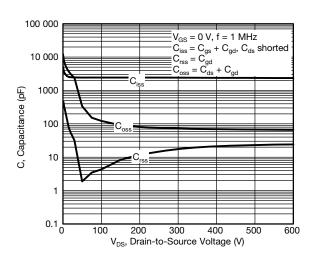


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

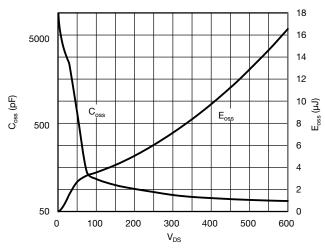


Fig. 6 - Coss and Eoss vs. VDS



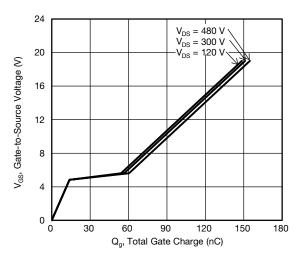


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

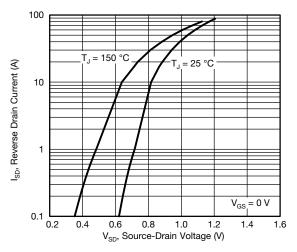


Fig. 8 - Typical Source-Drain Diode Forward Voltage

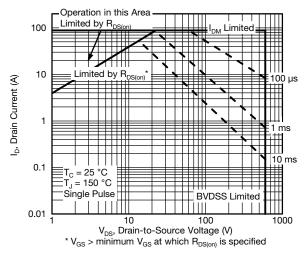


Fig. 9 - Maximum Safe Operating Area

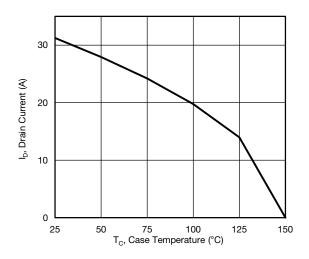


Fig. 10 - Maximum Drain Current vs. Case Temperature

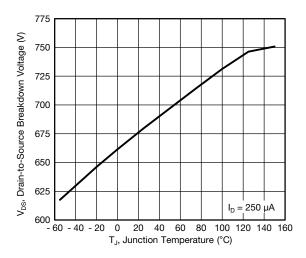


Fig. 11 - Temperature vs. Drain-to-Source Voltage



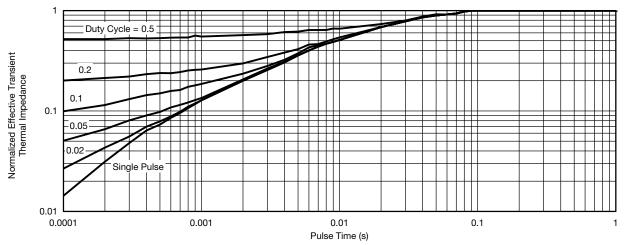


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

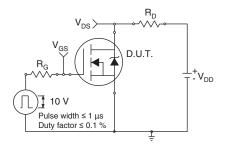


Fig. 13 - Switching Time Test Circuit

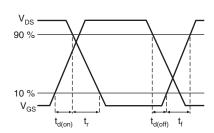


Fig. 14 - Switching Time Waveforms

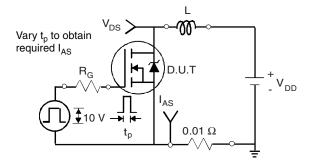


Fig. 15 - Unclamped Inductive Test Circuit

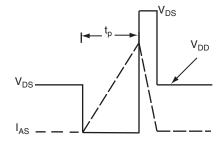


Fig. 16 - Unclamped Inductive Waveforms

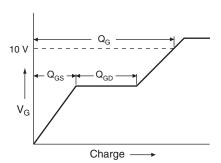


Fig. 17 - Basic Gate Charge Waveform

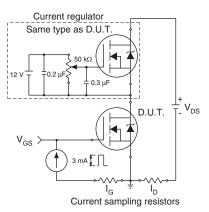
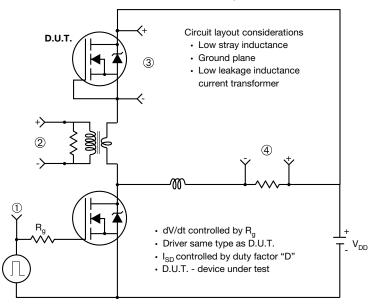


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



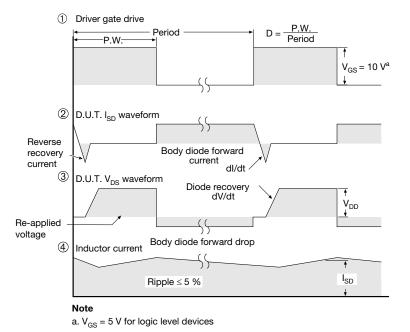


Fig. 19 - For N-Channel

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# TO-220-1



DIM.	MILLIM	METERS	INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
Е	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

## Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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